

N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)		
100	0.030 at V _{GS} = 10 V	8.0		
100	0.045 at V _{GS} = 4.5 V	6.5		

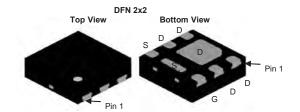
FEATURES

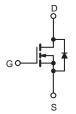
- **DT-Trench Power MOSFET**
- 100 % R_g Tested 100 % UIS Tested

COMPLIANT

APPLICATIONS

- · Primary Side Switch
- Synchronous Rectification





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current (T _{.1} = 150 °C)	T _A = 25 °C	- I _D	8.0		
Continuous Diain Current (1) = 150 °C)	T _A = 70 °C		5.2		
Pulsed Drain Current		I _{DM}	32	Α	
Continuous Source Current (Diode Conduction) ^a	I _S	8.0			
Maximum Power Dissipation ^a	T _A = 25 °C	- P _D	4.5	W	
Waxiiium Fower Dissipation	T _A = 70 °C		2.9	V V	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature) ^{b, c}			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	R _{thJA}	26	33	0C/M	
	Steady State		40	60	°C/W	

- a. Surface mounted on 1" x 1" FR4 board.
- b. The DFN2X2 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1		3	V	
Gate Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Coto Voltago Proin Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1	uА	
Zero Gate Voltage Drain Current		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 55 °C			5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	8			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$		0.030	0.036	Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 6 \text{ A}$		0.045	0.060	22	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 8 A		25		S	
Diode Forward Voltage ^a	V _{SD}	I _S = 1 A, V _{GS} = 0 V		0.75	1.2	V	
Dynamic ^b						•	
Total Gate Charge	Qg			15	45		
Gate-Source Charge	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 8 \text{ A}$		2.9		nC	
Gate-Drain Charge	Q_{gd}			1.8			
Gate Resistance	R _g			1.5		Ω	
Turn-On Delay Time	t _{d(on)}			14			
Rise Time	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 30 \Omega,$		12			
Turn-Off Delay Time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 6 \Omega$		50		ns	
Fall Time	t _f			12		1	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 3.2 A, dl/dt = 100 A/μs		60		1	

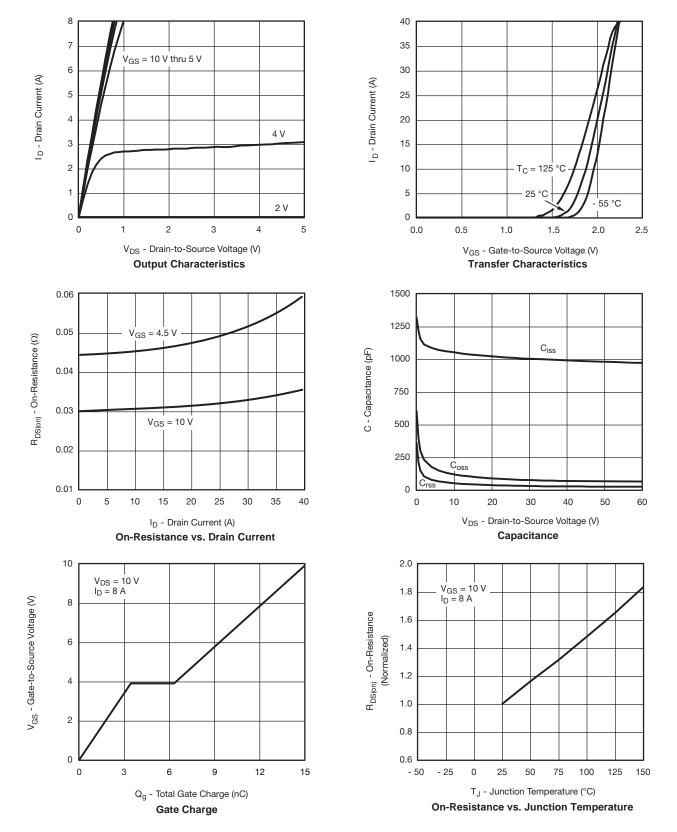
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

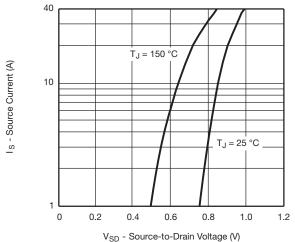
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

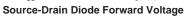


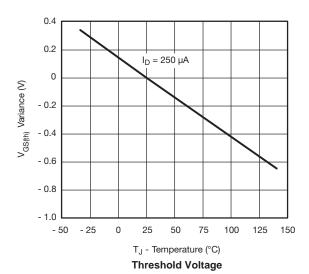
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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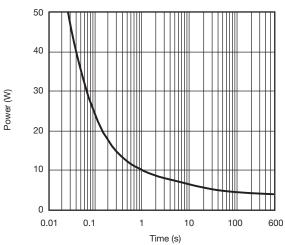




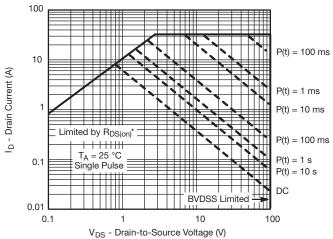


0.11 0.09 0.07 0.05 0.05 0.01 0 2 4 6 8 10

 $\label{eq:VGS} V_{GS} \text{ - Gate-to-Source Voltage (V)} \\$ On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

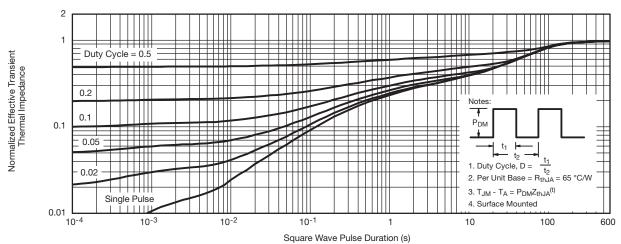


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

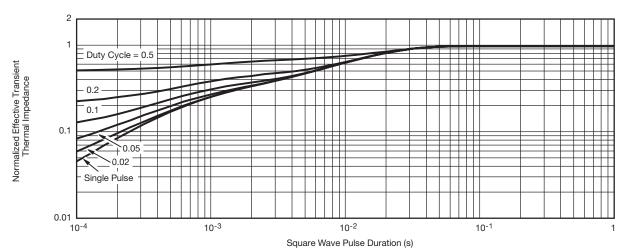
Safe Operating Area



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



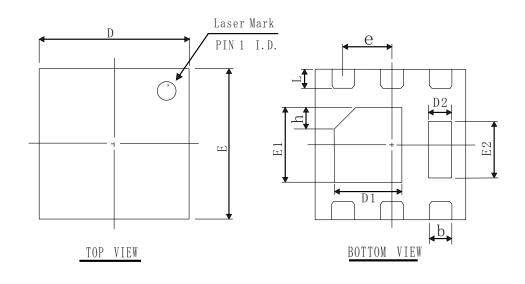
Normalized Thermal Transient Impedance, Junction-to-Ambient

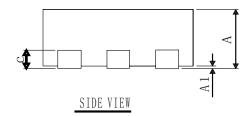


Normalized Thermal Transient Impedance, Junction-to-Case



DFN 2X2 PACKAGE OUTLINE





COMMON DIMENSIONS (UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.60	0.75	0.90
A 1	0.00	0.02	0.10
b	0.15	0.25	0.40
D	1.80	2.00	2.25
Е	1.80	2.00	2.25
D1	0.70	0.90	1.10
E1	0.75	1.00	1.20
D2	0.15	0.30	0.45
E2	0.45	0.75	0.95
L	0.15	0.25	0.40
h	0.15	0.25	0.40
С	0.203 REF		
е	0.65 BSC		

Other thickness dimensions are as follows

A	0.50	0.55	0.60
A	0.40	0.45	0.50





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